

XC17S200APDG8I Information


For Reference Only

Part Number [XC17S200APDG8I](#)
Manufacturer Xilinx Inc.
Category Integrated Circuits (ICs)
[Memory - Configuration Proms for FPGAs](#)
Description IC PROM SER 200K I-TEMP 8-DIP
Package 8-DIP (0.300", 7.62mm)
 For the pricing/inventory/lead time, please contact us
 Website: <https://www.heisener.com>
 E-mail: salesdept@heisener.com


[Request a Quote](#)
Certified Quality

Heisener's commitment to quality has shaped our processes for sourcing, testing, shipping, and every step in between. This foundation underlies each component we sell.


XC17S200APDG8I Specifications

Manufacturer Part Number	XC17S200APDG8I
Manufacturer	Xilinx Inc.
Category	Integrated Circuits (ICs) Memory - Configuration Proms for FPGAs
Package	8-DIP (0.300", 7.62mm)
Series	-
Programmable Type	OTP
Memory Size	2Mb
Voltage - Supply	3 V ~ 3.6 V
Operating Temperature	-40°C ~ 85°C
Package / Case	8-DIP (0.300", 7.62mm)
Supplier Device Package	8-PDIP
Report errors?	

XC17S200APDG8I Guarantees

Quality Guarantees

We provide 90 days warranty. *

If the items you received were not in perfect quality, we would be responsible for your refund or replacement, but the items must be returned in their original condition.


Service Guarantees

We guarantee 100% customer satisfaction.

Our experienced sales team and tech support team back our services to satisfy all our customers.

XC17S200APDG8I Payment Methods



XC17S200APDG8I Shipping Methods



If you have any question about XC17S200APDG8I, please do not hesitate to contact us!

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